



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-13
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STD2N80K5	CMDP*VJ80B52	A	SHENZHEN B/E	2016-05-13
Amount		UoM	Unit type	ST ECOPACK Grade
310.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.5-6.1-2.3	3	GULL WING	
Comment	TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CMDP*VJ80852					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.599	mg	supplier	die	Silicon (Si)	7440-21-3		2.492	mg	958830	8039
				supplier	metallization	Aluminium (Al)	7429-90-5		0.046	mg	17699	148
				supplier	Passivation	Silicon Nitride	12033-89-5		0.011	mg	4232	35
				supplier	Passivation	Silicon Oxide	7631-86-9		0.026	mg	10004	84
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	385	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.017	mg	6541	55
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.006	mg	2309	19
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	529523
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	2001	1065
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1490
Soft solder	Solder	2.556	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.441	mg	955008	7874
				supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	25039	206
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	19953	165
Bonding wires	Other inorganic materials	0.098	mg	supplier	wire	Copper (Cu)	7440-50-8		0.098	mg	1000000	316
				supplier	wire	Copper (Cu)	7440-50-8		0.098	mg	1000000	316
Encapsulation	Other Organic Materials	138.758	mg	supplier	mold compound	Silica, vitreous	60676-86-0		121.413	mg	874998	391655
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		5.550	mg	39997	17903
				supplier	mold compound	Epoxy Resin	25068-38-6		4.163	mg	30002	13429
				supplier	mold compound	phenol resin	29690-82-2		6.938	mg	50001	22381
				supplier	mold compound	Carbon black	1333-86-4		0.694	mg	5002	2239
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3371